



Customer No.: 31561
Docket No. 10796-US-PA
Application No.: 10/710,344

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Ho et al.

Application No. : 10/710,344

Filed : July 2, 2004

For : CHIP PACKAGE STRUCTURE WITH DUAL HEAT SINKS

Art Unit : 2826

Examiner : QUINTO, KEVIN V

TRANSMITTAL LETTER

002-1-571-273-2885

(Via fax: 1+2 pages)

Assistant Commissioner for Patents
Alexandria, VA 22314

Dear Sir,

In response to the Notice of Allowance and Fee(s) due, dated September 9, 2005, transmitted herewith please find the Issue Fee Transmittal (PTOL-85B) in duplicate.

Please charge the fee in the amount of \$1700.00 for Issue Fee and Publication Fee to Account No. 50-2620 (Order No.: 10796-US-PA).

Please be advised that the title of the invention should be amended as shown above according to the response to the first Office Action mailed June 27, 2005.

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date: Dec. 7, 2005

By: Belinda Lee
Belinda Lee
Registration No.: 46,863

Please send future correspondence to:

7F -1, No. 100, Roosevelt Rd.,

Sec. 2, Taipei 100, Taiwan, R.O.C.

Tel: 886-2-2369 2800

Fax: 886-2-2369 7233 / 886-2-2369 7234

E-MAIL: BELINDA@JCIPGroup.com.tw; USA@JCIPGroup.com.tw